



Polyamide 66 Prime Compound

Description:

Polyamide 66 compound unfilled grade for injection moulding applications, available in customer colors also Heat Stabilized (H) and UV Stabilized (UV)

General

General			
Density	ISO 1183	1.14	g/cm³
Water absorption (23°C;50%RH)	ASTM D570	1.3	%
Linear mould shrinkage	ASTM D955	1.5	%
Thermal			
HDT/A (1,82MPa)	ISO 75A	90	°C
Vicat softening point (B50 (50N))	ISO 306	240	°C
Mechanical			
Izod notched impact strength (23°C)	ISO 180	5	kJ/m²
Charpy notched impact strength (23 °C)	ISO 179	6	kJ/m²
Charpy unnotched impact strength (23 °C)	ISO 179	80	kJ/m²
Tensile stress at yield	ISO 527	80	MPa
Tensile stress at break	ISO 527	75	MPa
Elongation at break	ISO 527	25	%
Flex modulus	ISO 178	2900	MPa
Flammability			
Glow wire flammability index (2,0 mm)	IEC 60695-2-12	850	°C
√arious			
Surface resistivity	IEC 60093	10E14	Ohm

IEC 60243-1

IEC 60112

18

600

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Ravago Group Headquarters

Dielectric rigidity (Oil 1mm)

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kV/mm